

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC093N04LS G	**Issued**	14. September 2018
MA#	MA003606594		
Package	PG-TDSON-8-40	**Weight***	111.60 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.804	0.72	0.72	7204	7204
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		131	
	non noble metal	iron	7439-89-6	0.049	0.04		436	
	non noble metal	copper	7440-50-8	48.649	43.60	43.65	435930	436497
wire	non noble metal	copper	7440-50-8	0.062	0.06	0.06	555	555
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		758	
	plastics	epoxy resin	-	6.683	5.99		59887	
	inorganic material	silicondioxide	60676-86-0	35.532	31.84	37.91	318388	379033
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13620	13620
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1420	1420
solder	non noble metal	tin	7440-31-5	0.022	0.02		199	
	noble metal	silver	7440-22-4	0.028	0.02		249	
	non noble metal	lead	7439-92-1	1.060	0.95	0.99	9500	9948
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		46	
	non noble metal	iron	7439-89-6	0.017	0.02		152	
	non noble metal	copper	7440-50-8	16.910	15.15	15.17	151525	151723
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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